

SLAS859A - MAY 2012 - REVISED SEPTEMBER 2012

# 2V<sub>RMS</sub> DirectPath<sup>™</sup>, 112/106/100dB Audio Stereo DAC with 32-bit, 384kHz PCM Interface

Check for Samples: PCM5100A, PCM5101A, PCM5102A

#### **FEATURES**

- Market-Leading Low Out-of-Band Noise
- Selectable Digital-Filter Latency and Performance
- No DC Blocking Capacitors Required
- Integrated Negative Charge Pump
- Internal Pop-Free Control For Sample-Rate Changes Or Clock Halts
- Intelligent Muting System; Soft Up or Down Ramp and Analog Mute For 120dB Mute SNR With Popless Operation.
- Integrated High-Performance Audio PLL With BCK Reference To Generate SCK Internally
- Supports 1.8V Digital Input Interface
- Small 20-pin TSSOP Package

#### Typical Performance (3.3V Power Supply)

Parameter	PCM5102 / PCM5101 / PCM5100				
SNR	112 / 106 / 100dB				
Dynamic Range	112 / 106 / 100dB				
THD+N @ - 1dBFS	-93 / -92 / -90dB				
Full Scale Output	2.1V <sub>RMS</sub> (GND center)				
Normal 8x Oversampling Digital	al Filter Latency: 20t <sub>S</sub>				
Low Latency 8x Oversampling	Digital Filter Latency: 3.5t <sub>S</sub>				
Sampling Frequency	8kHz to 384kHz				
System Clock Multiples (f <sub>SCK</sub> ): 64, 128, 192, 256, 384, 512, 768, 1024, 1152, 1536, 2048, 3072; up to 50 MHz					

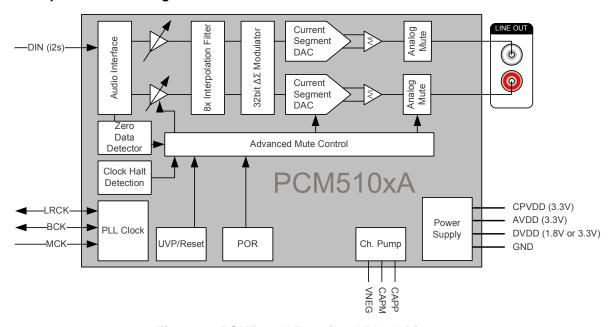


Figure 1. PCM510xA Functional Block Diagram

#### OTHER KEY FEATURES

- Accepts 16-, 24-, And 32-Bit Audio Data
- PCM Data Formats: I<sup>2</sup>S, Left-Justified
- Automatic Power-Save Mode When LRCK And BCK Are Deactivated.
- 1.8V or 3.3V Failsafe LVCMOS Digital Inputs
- Hardware Configuration
- Single Supply Operation:
  - 3.3V Analog, 1.8V or 3.3V Digital
- Integrated Power-On Reset

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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

#### **APPLICATIONS**

- A/V Receivers
- DVD, BD Players
- HDTV Receivers
- Applications Requiring 2V<sub>RMS</sub> Audio Output

#### DESCRIPTION

The PCM510xA devices are a family of monolithic CMOS integrated circuits that include a stereo digital-to-analog converter and additional support circuitry in a small TSSOP package. The PCM510xA uses the latest generation of TI's advanced segment-DAC architecture to achieve excellent dynamic performance and improved tolerance to clock jitter.

The PCM510xA provides 2.1V<sub>RMS</sub> ground centered outputs, allowing designers to eliminate DC blocking capacitors on the output, as well as external muting circuits traditionally associated with single supply line drivers.

The integrated line driver surpasses all other charge-pump based line drivers by supporting loads down to  $1k\Omega$ . By supporting loads down to  $1k\Omega$ , the PCM510xA can essentially drive up to 10 products in parallel. (LCD TV, DVDR, AV Receivers etc).

The integrated PLL on the device removes the requirement for a system clock (commonly known as master clock), allowing a 3-wire I<sup>2</sup>S connection and reducing system EMI.

Intelligent clock error and PowerSense under voltage protection utilizes a two level mute system for pop-free performance. Upon clock error or system power failure, the device digitally attenuates the data (or last known good data), then mutes the analog circuit

Compared with existing DAC technology, the PCM510xA family offers up to 20dB lower out-of-band noise, reducing EMI and aliasing in downstream amplifiers/ADCs. (from traditional 100kHz OBN measurements all the way to 3MHz)

The PCM510xA accepts industry-standard audio data formats with 16- to 32-bit data. Sample rates up to 384kHz are supported.

Table 1. Differences Between PCM510xA Devices

Part Number	Dynamic Range	SNR	THD
PCM5102A	112dB	112dB	-93dB
PCM5101A	106dB	106dB	-92dB
PCM5100A	100dB	100dB	-90dB

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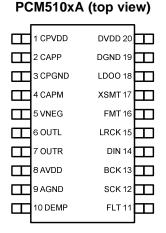


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#### **DEVICE INFORMATION**

### **TERMINAL FUNCTIONS, PCM510xA**



#### Table 2. TERMINAL FUNCTIONS, PCM510xA

TERMINAL			
NAME	NO.	I/O	DESCRIPTION
CPVDD	1	_	Charge pump power supply, 3.3V
CAPP	2	0	Charge pump flying capacitor terminal for positive rail
CPGND	3	_	Charge pump ground
CAPM	4	0	Charge pump flying capacitor terminal for negative rail
VNEG	5	0	Negative charge pump rail terminal for decoupling, -3.3V
OUTL	6	0	Analog output from DAC left channel
OUTR	7	0	Analog output from DAC right channel
AVDD	8		Analog power supply, 3.3V
AGND	9	_	Analog ground
DEMP	10	I	De-emphasis control for 44.1kHz sampling rate (1): Off (Low) / On (High)
FLT	11	I	Filter select : Normal latency (Low) / Low latency (High)
SCK	12	I	System clock input <sup>(1)</sup>
BCK	13	- 1	Audio data bit clock input <sup>(1)</sup>
DIN	14	- 1	Audio data input <sup>(1)</sup>
LRCK	15	I	Audio data word clock input <sup>(1)</sup>
FMT	16	I	Audio format selection: I <sup>2</sup> S (Low) / Left justified (High)
XSMT	17	I	Soft mute control <sup>(1)</sup> : Soft mute (Low) / soft un-mute (High)
LDOO	18	_	Internal logic supply rail terminal for decoupling, or external 1.8V supply terminal
DGND	19		Digital ground
DVDD	20	_	Digital power supply, 1.8V or 3.3V

(1) Failsafe LVCMOS Schmitt trigger input





#### **ABSOLUTE MAXIMUM RATINGS**

over operating free-air temperature range (unless otherwise noted)

		VALUE	UNIT	
Cupply \/altaga	AVDD, CPVDD, DVDD	-0.3 to 3.9		
Supply Voltage	LDOO wtih DVDD at 1.8V (See Figure 40 and Figure 42)	-0.3 to 2.25		
Digital Input Valtage	DVDD at 1.8V	-0.3 to 2.25	V	
Digital Input Voltage	DVDD at 3.3V	-0.3 to 3.9		
Analog Input Voltage		-0.3 to 3.9		
Operating Temperature Range	Operating Temperature Range –25 to 85			
Storage Temperature Range		-65 to 150	°C	

### THERMAL CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

	PARAMETER TEST CONDITIONS			TYP	MAX	UNIT
$\theta_{JA}$	Theta JA	High K		91.2		
ΨЈТ	Psi JT			1.0		
ΨЈВ	Psi JB			41.5		°C/W
$\theta_{JC}$	Theta JC	Тор		25.3		
$\theta_{JB}$	Theta JB			42.0		

### **ELECTRICAL CHARACTERISTICS**

	PARAMETER	TEST CONDITIONS	TEST CONDITIONS MIN TYP		UNIT		
	Resolution		16	Bits			
Data Fo	ormat (PCM Mode)		•				
	Audio data interface format		I <sup>2</sup> S, left justified				
	Audio data bit length		16, 24, 32-bit accepta	ble			
	Audio data format		MSB First, 2's Comple	ement			
fs <sup>(1)</sup>	Sampling frequency		8	384	kHz		
	System clock frequency		64, 128, 192, 256, 384, 512, 768, 1024, 1152, 1536, 2 3072 f <sub>SCK</sub> , up to 50Mhz				
Digital	Input/Output		·				
	Logic Family: 3.3V LVCMOS c	ompatible					
$V_{IH}$	Input logic level		0.7×DV <sub>DD</sub>		V		
$V_{IL}$	input logic level			$0.3 \times DV_{DD}$	V		
I <sub>IH</sub>	Input logic current	$V_{IN} = V_{DD}$		10	μA		
$I_{IL}$	input logic current	$V_{IN} = 0V$		-10	μΑ		
$V_{OH}$	Output logic level	$I_{OH} = -4mA$	0.8×DV <sub>DD</sub>		V		
$V_{OL}$	Output logic level	I <sub>OL</sub> = 4mA		$0.22 \times DV_{DD}$	V		
	Logic Family 1.8V LVCMOS co	ompatible					
$V_{IH}$	Input logic level		0.7×DV <sub>DD</sub>		V		
$V_{IL}$	input logic level			$0.3 \times DV_{DD}$	V		
I <sub>IH</sub>	Input logic current	$V_{IN} = V_{DD}$		10	μA		
$I_{\parallel L}$	input logic current	$V_{IN} = 0V$		-10	μΛ		
$V_{OH}$	Output logic level	$I_{OH} = -2mA$	0.8×DV <sub>DD</sub>		V		
$V_{OL}$	Output logic level	$I_{OL} = 2mA$		$0.22 \times DV_{DD}$	v		

<sup>(1)</sup> One sample time si defined as the reciprocal of the sampling frequency.  $1t_S = 1/f_S$ 



### **ELECTRICAL CHARACTERISTICS (continued)**

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Dynam	ic Performance (PCM Mode) <sup>(2)(3)</sup>	(Values shown for three devices	PCM5102/PCM51	101/PCM5100)		
		f <sub>S</sub> = 48kHz		-93/-92/-90	-83/ -82/ -80	
	THD+N at -1 dBFS <sup>(3)</sup>	f <sub>S</sub> = 96kHz		-93/-92/-90		
		$f_S = 192kHz$		-93/-92/-90		
	Dynamic range (3)	EIAJ, A-weighted, f <sub>S</sub> = 48kHz	106/ 100/ 95	112/106/100		
		EIAJ, A-weighted, f <sub>S</sub> = 96kHz		112/106/100		
		EIAJ, A-weighted, f <sub>S</sub> = 192kHz		112/106/100		
	Signal-to-noise ratio (3)	EIAJ, A-weighted, f <sub>S</sub> = 48kHz		112/106/100		dB
		EIAJ, A-weighted, f <sub>S</sub> = 96kHz		112/106/100		
		EIAJ, A-weighted, f <sub>S</sub> = 192kHz		112/106/100		
	Signal to noise ratio with analog mute <sup>(3)(4)</sup>	EIAJ, A-weighted, f <sub>S</sub> = 48kHz	113	123		
	analog mute(3)(4)	EIAJ, A-weighted, f <sub>S</sub> = 96kHz		123		
		EIAJ, A-weighted, f <sub>S</sub> = 192kHz		123		
	Channel Separation	f <sub>S</sub> = 48 kHz	100/ 95/ 90	109/103/97		
		f <sub>S</sub> = 96kHz		109/103/97		
		f <sub>S</sub> = 192kHz		109/103/97		
Analog	Output					
	Output voltage			2.1		V <sub>RMS</sub>
	Gain error		-6	±2.0	6	% of FSR
	Gain mismatch, channel-to- channel		-6	±2.0	6	% of FSR
	Bipolar zero error	At bipolar zero	<b>-</b> 5	±1.0	5	mV
	Load impedance		1			kΩ
Filter C	Characteristics-1: Normal					
	Pass band				0.45f <sub>S</sub>	
	Stop band		0.55f <sub>S</sub>			
	Stop band attenuation		-60			-10
	Pass-band ripple				±0.02	dB
	Delay time			20t <sub>S</sub>		s
Filter C	Characteristics–2: Low Latency					
	Pass band				0.47f <sub>S</sub>	
	Stop band		0.55f <sub>S</sub>			
	Stop band attenuation		-52			.ID
	Pass-band ripple				±0.0001	dB
	Delay time			3.5t <sub>S</sub>		s

<sup>(2)</sup> Filter condition: THD+N: 20Hz HPF, 20kHz AES17 LPF Dynamic range: 20Hz HPF, 20kHz AES17 LPF, A-weighted Signal-to-noise ratio: 20Hz HPF, 20kHz AES17 LPF, A-weighted Channel separation: 20Hz HPF, 20kHz AES17 LPF Analog performance specifications are measured using the System Two Cascade™ audio measurement system by Audio Precision™ in the RMS mode.

<sup>(3)</sup> Output load is  $10k\Omega$ , with  $470\Omega$  output resistor and a 2.2nF shunt capacitor (see recommended output filter).

<sup>(4)</sup> Assert XSMT or both L-ch and R-ch PCM data are BPZ





### **ELECTRICAL CHARACTERISTICS (continued)**

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Power Su	upply Requirements					
$DV_DD$	Digital supply voltage	Target DV <sub>DD</sub> = 1.8V	1.65	1.8	1.95	VDC
$DV_DD$	Digital supply voltage	Target DV <sub>DD</sub> = 3.3V	3.0	3.3	3.6	
AV <sub>DD</sub>	Analog supply voltage		3.0	3.3	3.6	VDC
CPV <sub>DD</sub>	Charge-pump suply voltage		3.0	3.3	3.6	
		f <sub>S</sub> = 48kHz		7		
$I_{DD}$	DV <sub>DD</sub> supply current at 1.8V <sup>(5)</sup>	f <sub>S</sub> = 96kHz		8		mA
		f <sub>S</sub> = 192kHz		9		
		f <sub>S</sub> = 48kHz		7		
$I_{DD}$	DV <sub>DD</sub> supply current at 1.8V <sup>(6)</sup>	f <sub>S</sub> = 96kHz		8		mA
		f <sub>S</sub> = 192kHz		9		
DD	DV <sub>DD</sub> supply current at 1.8V <sup>(7)</sup>			0.3		mA
		f <sub>S</sub> = 48kHz		7	12	
DD	DV <sub>DD</sub> supply current at 3.3V <sup>(5)</sup>	f <sub>S</sub> = 96kHz		8		mA
		f <sub>S</sub> = 192kHz		9		
		f <sub>S</sub> = 48kHz		8	13	
DD	DV <sub>DD</sub> supply current at 3.3V <sup>(6)</sup>	f <sub>S</sub> = 96kHz		9		mA
		f <sub>S</sub> = 192kHz		10		
DD	DV <sub>DD</sub> supply current at 3.3V <sup>(7)</sup>			0.5	0.8	mA
00	AVpp / CPVpp Supply	f <sub>S</sub> = 48kHz		11	16	
$I_{CC}$ AV <sub>DD</sub> / CPV <sub>DD</sub> S Current <sup>(5)</sup>		$f_S = 96kHz$		11		mA
	Current	f <sub>S</sub> = 192kHz		11		
		$f_S = 48kHz$		22	32	
СС	AV <sub>DD</sub> / CPV <sub>DD</sub> Supply	$f_S = 96kHz$		22		mA
	Current <sup>(6)</sup>	$f_S = 192kHz$		22		1111
l <sub>cc</sub>	AV <sub>DD</sub> / CPV <sub>DD</sub> Supply Current <sup>(7)</sup>	$f_S = n/a$		0.2	0.4	mA
	Current	f <sub>S</sub> = 48kHz		48.9	185	
	Power Dissipation, DV <sub>DD</sub> =	$f_S = 96kHz$		50.7	103	mW
	1.8V <sup>(5)</sup>	-				IIIVV
		f <sub>S</sub> = 192kHz		52.5	107	
	Power Dissipation, DV <sub>DD</sub> =	$f_S = 48kHz$		85.2	187	\^/
	1.8V <sup>(6)</sup>	f <sub>S</sub> = 96kHz		87.0		mW
	Power Dissipation, $DV_{DD} = \frac{1}{2} \frac{1}{2}$	$f_S = 192kHz$ $f_S = n/a$ (Power Down Mode)		88.8 1.2		mW
	1.8V <sup>(7)</sup>	f 401.11-		FC 4	00.4	
	Power Dissipation, DV <sub>DD</sub> =	$f_S = 48kHz$		59.4	92.4	
	3.3V <sup>(5)</sup>	f <sub>S</sub> = 96kHz		62.7		mW
		f <sub>S</sub> = 192kHz		66.0		
	Power Dissipation, DV <sub>DD</sub> =	f <sub>S</sub> = 48kHz		99.0	148.5	
	3.3V <sup>(6)</sup>	$f_S = 96kHz$		102.3		mW
		f <sub>S</sub> = 192kHz		105.6		
	Power Dissipation, DV <sub>DD</sub> = 3.3V <sup>(7)</sup>	f <sub>S</sub> = n/a (Power Down Mode)		2.3	4.0	mW

<sup>(5)</sup> Input is Bipolar Zero data.

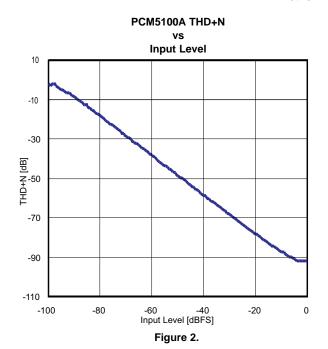
<sup>(6)</sup> Input is 1kHz -1dBFS data

<sup>(7)</sup> Power Down Mode



### TYPICAL CHARACTERISTICS

All specifications at  $T_A = 25$ °C,  $AV_{DD} = CPV_{DD} = DV_{DD} = 3.3$ V,  $f_S = 48$ kHz, system clock = 512  $f_S$  and 24-bit data unless otherwise noted.



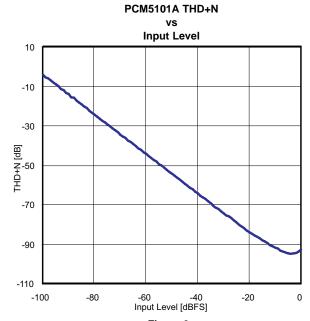


Figure 3.

#### PCM5102A THD+N

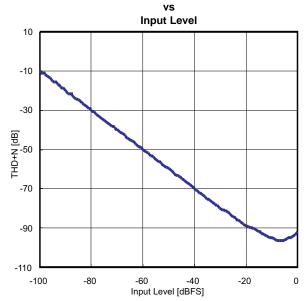
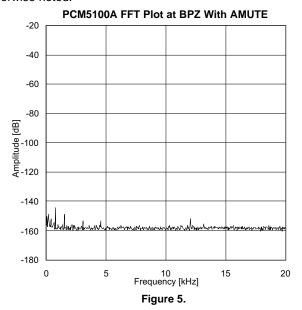
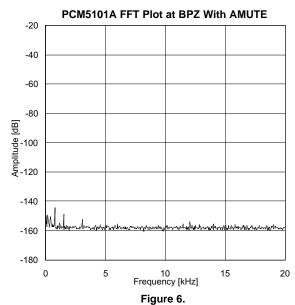


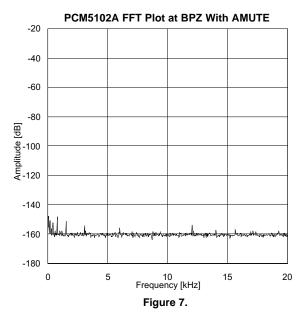
Figure 4.



### **TYPICAL CHARACTERISTICS (continued)**

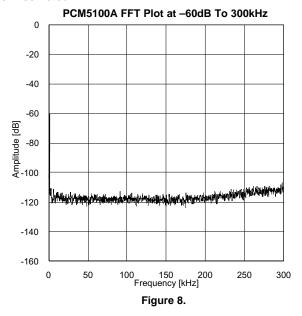


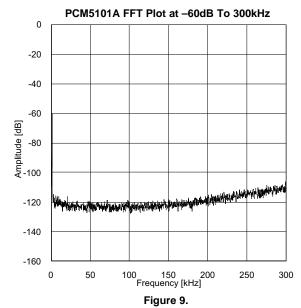


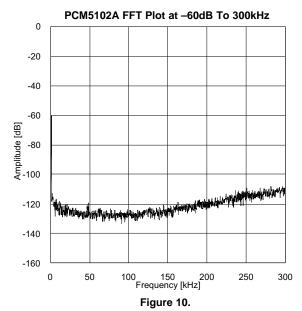




# **TYPICAL CHARACTERISTICS (continued)**









#### **APPLICATION INFORMATION**

#### **Reset and System Clock Functions**

#### **Power-On Reset Function**

The PCM510xA includes a power-on reset function shown in Figure 11. With  $V_{DD} > 2.8V$ , the power-on reset function is enabled. After the initialization period, the PCM510xA is set to its default reset state.

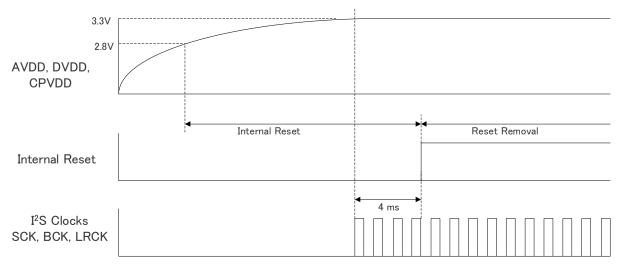


Figure 11. Power-On Reset Timing, DVDD = 3.3V

The PCM510xA includes a power-on reset function shown in Figure 12 operating at DVDD=1.8V. With AVDD greater than approximately 2.8V, and PVDD greater than approximately 2.8V, and DVDD greater than approximately 1.5V, the power-on reset function is enabled. After the initialization period, the PCM510xA is set to its default reset state.

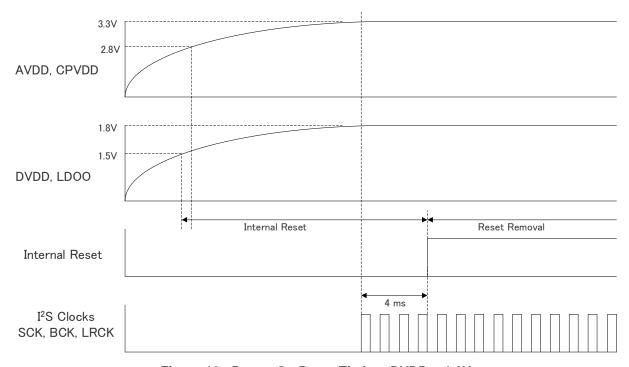


Figure 12. Power-On Reset Timing, DVDD = 1.8V



### **System Clock Input**

The PCM510xA requires a system clock to operate the digital interpolation filters and advanced segment DAC modulators. The system clock is applied at the SCK input (pin 12) and supports up to 50MHz. The PCM510xA system-clock detection circuit automatically senses the system-clock frequency. Common audio sampling frequencies of 8kHz, 16kHz, 32kHz - 44.1kHz - 48kHz, 88.2kHz - 96kHz, 176.4kHz -192kHz, and 384kHz with ±4% tolerance are supported. The sampling frequency detector sets the clock for the digital filter, Delta Sigma Modulator (DSM) and the Negative Charge Pump (NCP) automatically. Table 3 shows examples of system clock frequencies for common audio sampling rates.

SCK rates that are not common to standard audio clocks, between 1MHz and 50MHz, are only supported in software mode, available only in the PCM512x and PCM514x devices, by configuring various PLL and clock-divider registers. This programmability allows the device to become a clock master and drive the host serial port with LRCK and BCK, from a non-audio related clock (for example, using 12MHz to generate 44.1kHz (LRCK) and 2.8224MHz (BCK) ).

Figure 13 shows the timing requirements for the system clock input. For optimal performance, use a clock source with low phase jitter and noise.

Sampling		System Clock Frequency (f <sub>SCK</sub> ) (MHz)										
Frequency	64 f <sub>S</sub>	128 f <sub>S</sub>	192 f <sub>S</sub>	256 f <sub>S</sub>	384 f <sub>S</sub>	512 f <sub>S</sub>	768 f <sub>S</sub>	1024 f <sub>S</sub>	1152 f <sub>S</sub>	1536 f <sub>S</sub>	2048 f <sub>S</sub>	3072 f <sub>S</sub>
8 kHz	_(1)	1.0240 <sup>(2)</sup>	1.5360 <sup>(2)</sup>	2.0480	3.0720	4.0960	6.1440	8.1920	9.2160	12.2880	16.3840	24.5760
16 kHz	_(1)	2.0480(2)	3.0720 <sup>(2)</sup>	4.0960	6.1440	8.1920	12.2880	16.3840	18.4320	24.5760	36.8640	49.1520
32 kHz	_(1)	4.0960 <sup>(2)</sup>	6.1440 <sup>(2)</sup>	8.1920	12.2880	16.3840	24.5760	32.7680	36.8640	49.1520	_(1)	_(1)
44.1 kHz	_(1)	5.6488 <sup>(2)</sup>	8.4672 <sup>(2)</sup>	11.2896	16.9344	22.5792	33.8688	45.1584	_(1)	_(1)	_(1)	_(1)
48 kHz	_(1)	6.1440 <sup>(2)</sup>	9.2160 <sup>(2)</sup>	12.2880	18.4320	24.5760	36.8640	49.1520	_(1)	_(1)	_(1)	_(1)
88.2 kHz	_(1)	11.2896 <sup>(2)</sup>	16.9344	22.5792	33.8688	45.1584	_(1)	_(1)	_(1)	_(1)	_(1)	_(1)
96 kHz	_(1)	12.2880 <sup>(2)</sup>	18.4320	24.5760	36.8640	49.1520	_(1)	_(1)	_(1)	_(1)	_(1)	_(1)
176.4 kHz	_(1)	22.5792	33.8688	45.1584	_(1)	_(1)	_(1)	_(1)	_(1)	_(1)	_(1)	_(1)
192 kHz	_(1)	24.5760	36.8640	49.1520	_(1)	_(1)	_(1)	_(1)	_(1)	_(1)	_(1)	_(1)
384 kHz	24.5760	49.1520	_(1)	_(1)	_(1)	_(1)	_(1)	_(1)	_(1)	_(1)	_(1)	_(1)

Table 3. System Master Clock Inputs for Audio Related Clocks

- (1) This system clock rate is not supported for the given sampling frequency.
- (2) This system clock rate is supported by PLL mode.

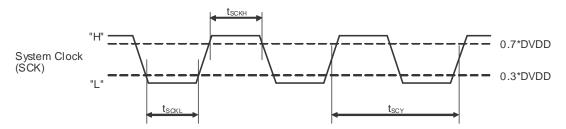


Figure 13. Timing Requirements for SCK Input

Table 4. Timing Requirements for SCK Input

	Parameters	Min	Max	Unit		
t <sub>SCY</sub>	System clock pulse cycle time	20	1000	ns		
	System clock pulse width, High	DVDD=1.8V	8		20	
t <sub>SCKH</sub>		DVDD=3.3V	9		ns	
		DVDD=1.8V	8			
<sup>T</sup> SCKL	System clock pulse width, Low	DVDD=3.3V	9		ns	



#### **System Clock PLL Mode**

The system clock PLL mode allows designers to use a simple 3-wire I<sup>2</sup>S audio source when driving the DAC. The 3-wire source reduces the need for a high frequency SCK, making PCB layout easier, and reduces high frequency electromagnetic interference.

The device starts up expecting an external SCK input, but if BCK and LRCK start correctly while SCK remains at ground level for 16 successive LRCK periods, then the internal PLL starts, automatically generating an internal SCK from the BCK reference. The PCM510xA disables the internal PLL when an external SCK is supplied; specific BCK rates are required to generate an appropriate master clock. Table 5 describes the minimum and maximum BCK per LRCK for the integrated PLL to automatically generate an internal SCK.

Table 5. BCK Rates (MHz) by LRCK Sample Rate for PCM510xA PLL Operation

	BCK (f <sub>S</sub> )			
Sample f (kHz)	32	64		
8	-	-		
16	-	1.024		
32	1.024	2.048		
44.1	1.4112	2.8224		
48	1.536	3.072		
96	3.072	6.144		
192	6.144	12.288		
384	12.288	24.576		

#### **Audio Data Interface**

#### **Audio Serial Interface**

The audio interface port is a 3-wire serial port, including LRCK (pin 15), BCK (pin 13), and DIN (pin 14). BCK is the serial audio bit clock, used to clock the serial data present on DIN into the serial shift register of the audio interface. Serial data is clocked into the PCM510xA on the rising edge of BCK. LRCK is the serial audio left/right word clock.

Table 6. PCM510xA Audio Data Formats, Bit Depths and Clock Rates

CONTROL MODE	FORMAT	DATA BITS	MAX LRCK FREQUENCY [f <sub>S</sub> ]	SCK RATE [x f <sub>S</sub> ]	BCK RATE [x f <sub>S</sub> ]
Hardware Control	I <sup>2</sup> S/LJ	32, 24, 20, 16	Up to 192kHz	128 – 3072 (≤50MHz)	64, 48, 32
			384kHz	64, 128	64, 48, 32

The PCM510xA requires the synchronization of LRCK and system clock, but does not need a specific phase relation between LRCK and system clock.

If the relationship between LRCK and system clock changes more than ±5 SCK, internal operation is initialized within one sample period and analog outputs are forced to the bipolar zero level until resynchronization between LRCK and system clock is completed.

If the relationship between LRCK and BCK are invalid more than 4 LRCK periods, internal operation is initialized within one sample period and analog outputs are forced to the bipolar zero level until resynchronization between LRCK and BCK is completed.

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### **PCM Audio Data Formats and Timing**

The PCM510xA supports industry-standard audio data formats, including standard I<sup>2</sup>S and left-justified. Data formats are selected using the FMT (pin 16), Low for I<sup>2</sup>S, and High for Left-justified.

All formats require binary 2s complement, MSB-first audio data. Figure 14 shows a detailed timing diagram for the serial audio interface.

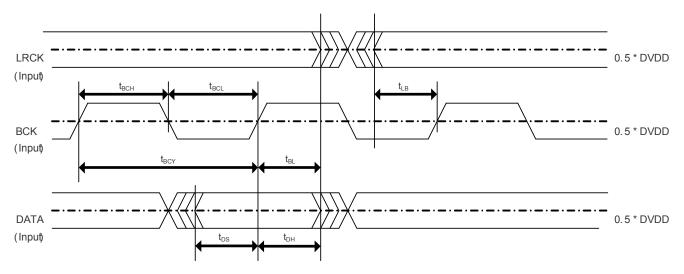
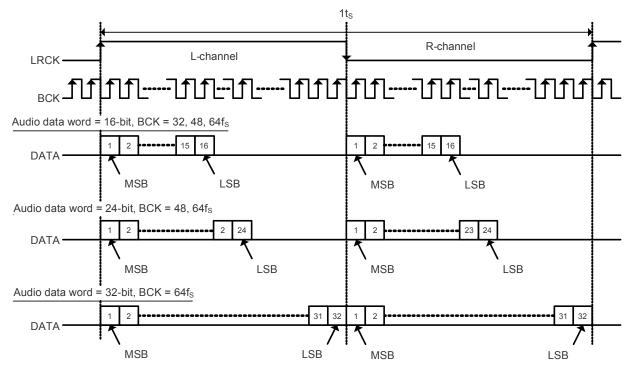


Figure 14. PCM510xA Serial Audio Timing - Slave

**Table 7. Audio Interface Slave Timing** 

t <sub>BCY</sub> BCK Pulse Cycle Time 40 r   t <sub>BCL</sub> BCK Pulse Width LOW 16 r   t <sub>BCH</sub> BCK Pulse Width HIGH 16 r   t <sub>BL</sub> BCK Rising Edge to LRCK Edge 8 r   t <sub>LB</sub> LRCK Edge to BCK Rising Edge 8 r   t <sub>DS</sub> DATA Set Up Time 8 r   t <sub>DH</sub> DATA Hold Time 8 r   f <sub>BCK</sub> BCK frequency @ DVDD=3.3V 24.576 M				•	
t <sub>BCL</sub> BCK Pulse Width LOW 16 r   t <sub>BCH</sub> BCK Pulse Width HIGH 16 r   t <sub>BL</sub> BCK Rising Edge to LRCK Edge 8 r   t <sub>LB</sub> LRCK Edge to BCK Rising Edge 8 r   t <sub>DS</sub> DATA Set Up Time 8 r   t <sub>DH</sub> DATA Hold Time 8 r   f <sub>BCK</sub> BCK frequency @ DVDD=3.3V 24.576 M		Parameters	Min	Max	Units
t <sub>BCH</sub> BCK Pulse Width HIGH 16 r   t <sub>BL</sub> BCK Rising Edge to LRCK Edge 8 r   t <sub>LB</sub> LRCK Edge to BCK Rising Edge 8 r   t <sub>DS</sub> DATA Set Up Time 8 r   t <sub>DH</sub> DATA Hold Time 8 r   f <sub>BCK</sub> BCK frequency @ DVDD=3.3V 24.576 M	$t_{BCY}$	BCK Pulse Cycle Time	40		ns
t <sub>BL</sub> BCK Rising Edge to LRCK Edge 8 r   t <sub>LB</sub> LRCK Edge to BCK Rising Edge 8 r   t <sub>DS</sub> DATA Set Up Time 8 r   t <sub>DH</sub> DATA Hold Time 8 r   f <sub>BCK</sub> BCK frequency @ DVDD=3.3V 24.576 M	$t_{BCL}$	BCK Pulse Width LOW	16		ns
t <sub>LB</sub> LRCK Edge to BCK Rising Edge 8 r   t <sub>DS</sub> DATA Set Up Time 8 r   t <sub>DH</sub> DATA Hold Time 8 r   f <sub>BCK</sub> BCK frequency @ DVDD=3.3V 24.576 M	t <sub>BCH</sub>	BCK Pulse Width HIGH	16		ns
tDS DATA Set Up Time 8 r   tDH DATA Hold Time 8 r   fBCK BCK frequency @ DVDD=3.3V 24.576 M	$t_{BL}$	BCK Rising Edge to LRCK Edge	8		ns
tDH DATA Hold Time 8 r   fBCK BCK frequency @ DVDD=3.3V 24.576 M	$t_{LB}$	LRCK Edge to BCK Rising Edge	8		ns
f <sub>BCK</sub> BCK frequency @ DVDD=3.3V 24.576 M	$t_{DS}$	DATA Set Up Time	8		ns
BOR 1 7	$t_{DH}$	DATA Hold Time	8		ns
f <sub>BCK</sub> BCK frequency @ DVDD=1.8V 12.288 M	f <sub>BCK</sub>	BCK frequency @ DVDD=3.3V		24.576	MHz
	f <sub>BCK</sub>	BCK frequency @ DVDD=1.8V		12.288	MHz





Left Justified Data Format; L-channel = HIGH, R-channel = LOW

Figure 15. Left Justified Audio Data Format

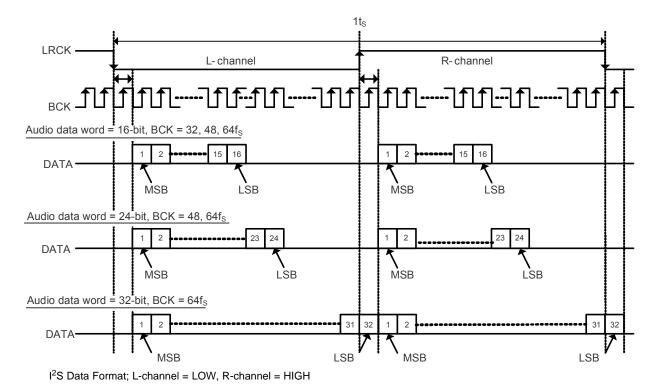


Figure 16. I<sup>2</sup>S Audio Data Format



### **Function Descriptions**

### Interpolation Filter

The PCM510xA provides 2 types of interpolation filter. Users can select which filter to use by using the FLT pin (pin11)

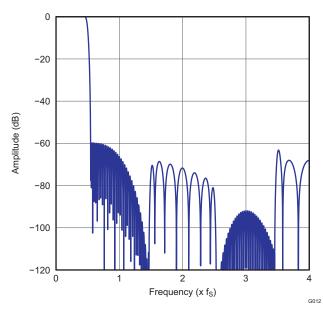
**Table 8. Digital Interpolation Filter Options** 

FLT Pin	Description
0	FIR Normal x8/x4/x2/x1 Interpolation Filters
1	IIR Low Latency x8/x4/x2/x1 Interpolation Filters

The Normal x8/x4/x2/x1 (bypass) Interpolation filter is programmed in 256 cycles in 1 sample time ( $t_S$ ) for sample rates from 8kHz to 384kHz.

Table 9. Normal x8 Interpolation Filter

Parameter	Condition	Value (Typ)	Value (Max)	Units
Filter Gain Pass Band	0 0.45f <sub>S</sub>		±0.02	dB
Filter Gain Stop Band	0.55f <sub>S</sub> 7.455f <sub>S</sub>	-60		dB
Filter Group Delay		22t <sub>S</sub>		s



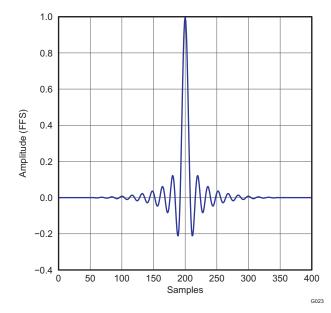


Figure 17. Normal x8 Interpolation Filter Frequency Response

Figure 18. Normal x8 Interpolation Filter Impulse Response



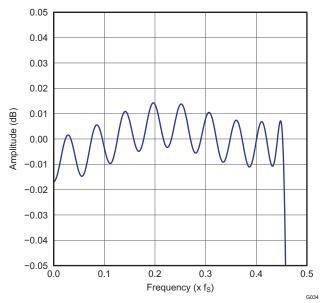


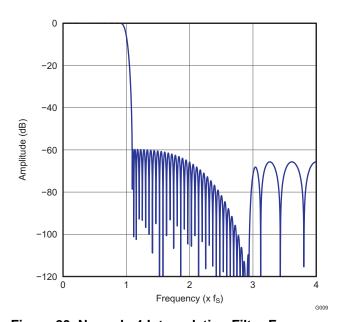
Figure 19. Normal x8 Interpolation Filter Passband Ripple



The Normal x4/x2/x1 (bypass) Interpolation filter is programmed in 256 cycles in 1 sample time ( $t_S$ ) for sample rates from 8kHz to 384kHz.

Table 10. Normal x4 Interpolation Filter

Parameter	Condition	Value (Typ)	Value (Max)	Units
Filter Gain Pass Band	0 0.45f <sub>S</sub>		±0.02	dB
Filter Gain Stop Band	0.55f <sub>S</sub> 7.455f <sub>S</sub>	-60		dB
Filter Group Delay		22t <sub>S</sub>		S



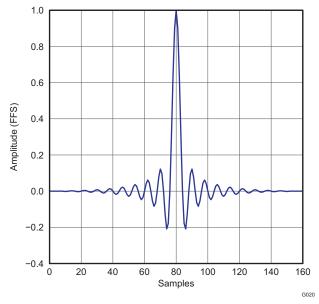


Figure 20. Normal x4 Interpolation Filter Frequency Response

Figure 21. Normal x4 Interpolation Filter Impulse Response

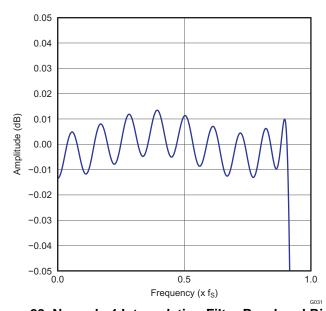


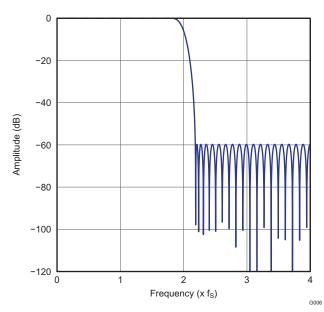
Figure 22. Normal x4 Interpolation Filter Passband Ripple



Normal x2 / x1(bypass) Interpolation filter is programmed in 256 cycles in 1 sample time ( $t_S$ ) for sample rates from 8kHz to 384kHz.

Table 11. Normal x2 Interpolation Filter

Parameter	Condition	Value (Typ)	Value (Max)	Units
Filter Gain Pass Band	0 0.45f <sub>S</sub>		±0.02	dB
Filter Gain Stop Band	0.55f <sub>S</sub> 7.455f <sub>S</sub>	-60		dB
Filter Group Delay		22t <sub>S</sub>		S



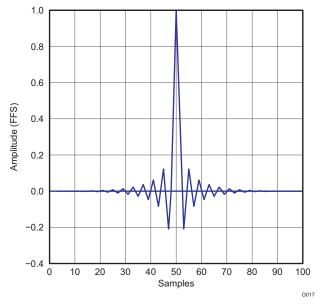


Figure 23. Normal x2 Interpolation Filter Frequency Response

Figure 24. Normal x2 Interpolation Filter Impulse Response

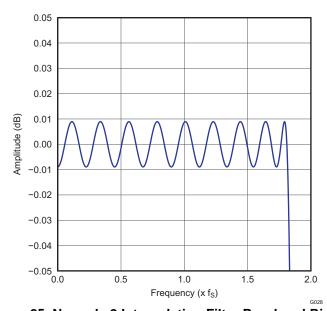


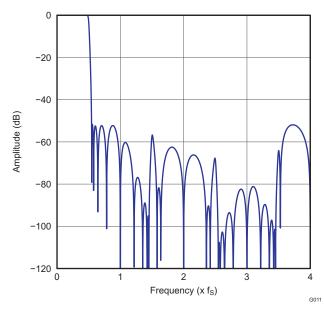
Figure 25. Normal x2 Interpolation Filter Passband Ripple



The low-latency x8 / x4 / x2 / x1 (bypass) Interpolation filter is programmed in 256 cycles 1 sample time ( $t_S$ ) for sample rates from 8kHz to 384kHz.

Table 12. Low latency x8 Interpolation Filter

Parameter	Condition	Value (Typ)	Units
Filter Gain Pass Band	0 0.45f <sub>S</sub>	±0.0001	dB
Filter Gain Stop Band	0.55f <sub>S</sub> 7.455f <sub>S</sub>	-52	dB
Filter Group Delay		3.5t <sub>S</sub>	S



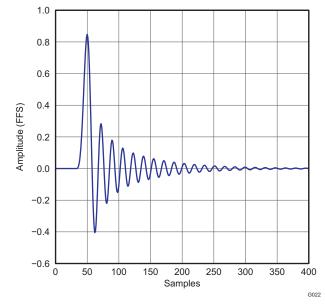


Figure 26. Low latency x8 Interpolation Filter Frequency Response

Figure 27. Low latency x8 Interpolation Filter Impulse Response

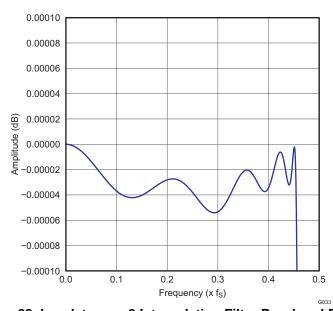
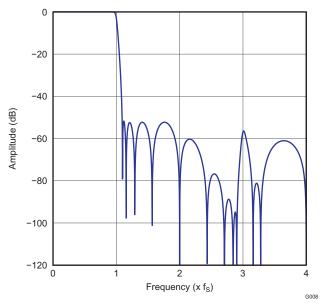


Figure 28. Low latency x8 Interpolation Filter Passband Ripple



### Table 13. Low latency x4 Interpolation Filter

Parameter	Condition	Value (Typ)	Units
Filter Gain Pass Band	0 0.45f <sub>S</sub>	±0.0001	dB
Filter Gain Stop Band	0.55f <sub>S</sub> 3.455f <sub>S</sub>	-52	dB
Filter Group Delay		3.5t <sub>S</sub>	s



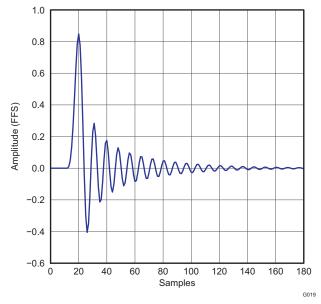


Figure 29. Low latency x4 Interpolation Filter Frequency Response

Figure 30. Low latency x4 Interpolation Filter Impulse Response

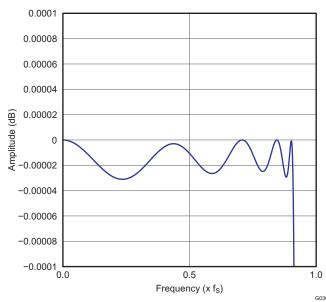
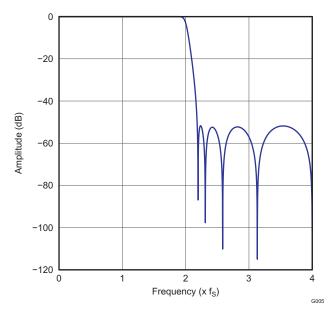


Figure 31. Low latency x4 Interpolation Filter Passband Ripple



Table 14. Low latency x2 Interpolation Filter

Parameter	Condition	Value (Typ)	Units
Filter Gain Pass Band	0 0.45f <sub>S</sub>	±0.0001	dB
Filter Gain Stop Band	0.55f <sub>S</sub> 1.455f <sub>S</sub>	-52	dB
Filter Group Delay		3.5t <sub>S</sub>	S



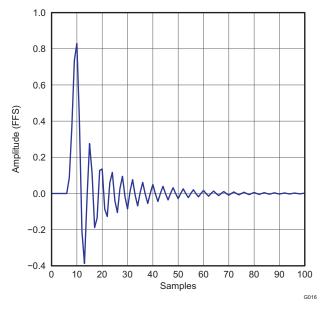


Figure 32. Low latency x2 Interpolation Filter Frequency Response

Figure 33. Low latency x2 Interpolation Filter Impulse Response

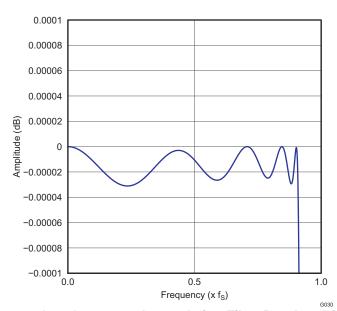


Figure 34. Low latency x2 Interpolation Filter Passband Ripple



#### **Zero Data Detect**

The PCM510xA has a zero-data detect function. When the device detects continuous zero data, it enters a full analog mute condition.

The PCM510xA counts zero data over 1024LRCKs (21ms @ 48kHz) before setting analog mute.

#### **Power Save Mode**

When any kind of clock error (SCK, BCK, and LRCK) or clock halt is detected, the PCM510xA enters Stand-by mode automatically. The current-segment DAC and Line driver are also powered down.

When BCK and LRCK halt to a low level for more than 1 second, the PCM510xA enters Power down mode automatically. Power-down mode includes the negative charge pump and Bias/Reference circuit power-down in addition to stand-by.

Whenever expected Audio clocks (SCK, BCK, LRCK) are applied to the PCM510xA, the device starts its powerup sequence automatically.

### XSMT Pin (Soft Mute and Soft Un-Mute)

For external digital control of the PCM510xA, the XSMT pin must be driven by an external digital host with a specific/minimum rise time  $(t_r)$  and fall time  $(t_f)$  for soft mute and soft un-mute. The PCM510xA requires  $t_r/t_f$  times of less than 20ns. In the majority of applications, this shouldn't be a problem, however, traces with high capacitance may have issues.

When the XSMT pin is shifted from high to low (3.3V to 0V), a soft digital attenuation ramp is started. -1dB attenuation will be applied every  $1t_S$  from 0dBFS to  $-\infty$ . This attenuation takes 104 sample times.

When the XSMT pin is shifted from low to high (0V to 3.3V), a soft digital "un-mute" is started. 1dB gain steps are applied every  $t_S$  from  $-\infty$  to 0dBFS. This ramp-up takes 104 sample times.

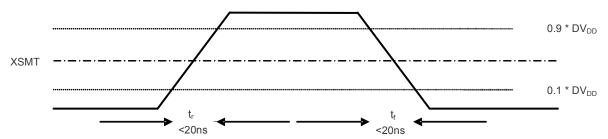


Figure 35. XSMT Timing for Soft Mute and Soft Un-Mute

**Table 15. XSMT Timing Parameters** 

Parameters	Min	Max	Unit
Rise time (t <sub>r</sub> )		20	ns
Fall time (t <sub>f</sub> )		20	ns

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### External Power Sense Undervoltage Protection mode (supported only when DVDD = 3.3V)

The XSMT pin can also be used to monitor a system voltage, such as the 24VDC LCD TV backlight, or 12VDC system supply using a potential divider created with two resistors. (See Figure 36)

- If the XSMT pin makes a transition from 1 to 0 over 6ms or more, the device will switch into external undervoltage protection mode. In this mode, two trigger levels are used.
- When XSMT pin level reaches 2V, soft mute process begins.
- When XSMT pin level reaches 1.2V, analog mute will engage, regardless of digital audio level, and analog shut down will begin. (For example, DAC circuitry powers down).

A timing diagram to show this is shown in Figure 37.

#### **NOTE**

The XSMT input pins voltage range is from -0.3V to DVDD + 0.3V. The ratio of external resistors must be considered within this input range. Any increase in power supply (such as power supply positive noise/ripple) can pull the XSMT pin higher than DVDD+0.3V.

For example, if the PCM510xA is monitoring a 12V input, and dividing the voltage by 4, then the voltage at XSMT during ideal power supply conditions will be 3V. If the voltage spikes any higher than 14.4V, then XSMT will see a voltage in excess of 3.6V (DVDD+0.3), potentially damaging the device.

Providing the divider is set appropriately, any DC voltage can be monitored.

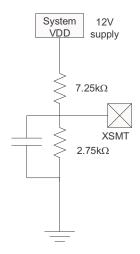


Figure 36. XSMT in External UVP Mode

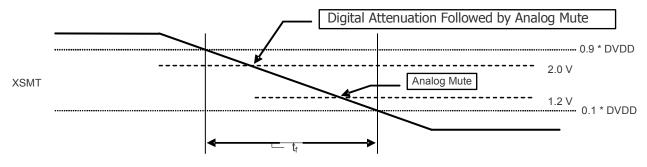


Figure 37. XSMT Timing for Undervoltage Protection



### Recommended Powerdown Sequence

With inadequate system design, the PCM510xA can exhibit some pop on power down. Pops are caused by the device not having enough time to detect power loss and start the muting process.

The PCM510xA evaluation board avoids audible pop with an electrolytic decoupling capacitor. This capacitor provides enough time between data loss from USB or S/PDIF and power supply loss for the muting process to take place.

The PCM510xA has two auto-mute functions to mute the device upon power loss (intentional or unintentional).

#### XSMT = 0

When the XSMT pin is pulled low, the incoming PCM data is attenuated to 0, closely followed by a hard analog mute. This process takes 150 sample times ( $t_s$ ) + 0.2mS.

As this mute time is mainly dominated by the sampling frequency, systems sampling at 192kHz will mute much faster than a 48kHz system.

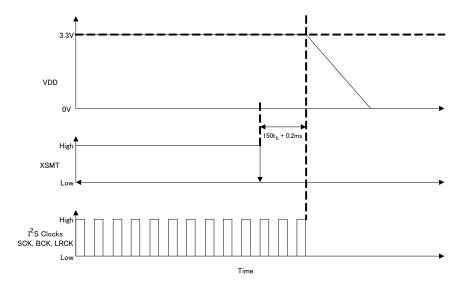
#### **Clock Error Detect**

When clock error is detected on the incoming data clock, the PCM510xA family switches to an internal oscillator, and continues to the drive the DAC, while attenuating the data from the last known value. Once this process is complete, the PCM510xA outputs will be hard muted to ground.

#### **Planned Shutdown**

These auto-muting processes can be manipulated by system designs to mute before power loss in the following ways:

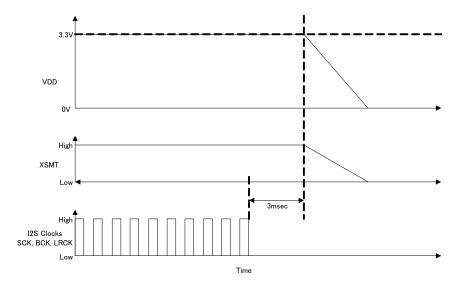
1. Assert XSMT low 150t<sub>S</sub> + 0.2mS before power is removed.



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2. Stop I<sup>2</sup>S clocks (SCK, BCK, LRCK) 3ms before powerdown as shown below:



### **Unplanned Shutdown**

Many systems use a low-noise regulator to provide an AVDD 3.3V supply for the DAC. The XSMT Pin can take advantage of such a feature to measure the pre-regulated output from the system SMPS to mute the DAC before the entire SMPS discharges. Figure 38 shows how to configure such a system to use the XSMT pin. The XSMT pin can also be used in parallel with a GPIO pin from the system microcontroller/DSP or Power Supply.

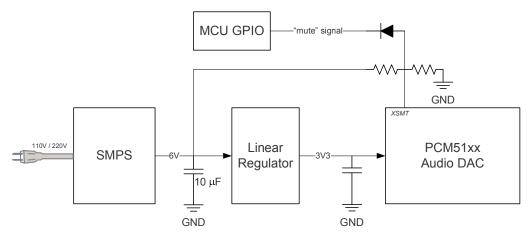


Figure 38. Using the XSMT Pin



### **Typical Application Circuits**

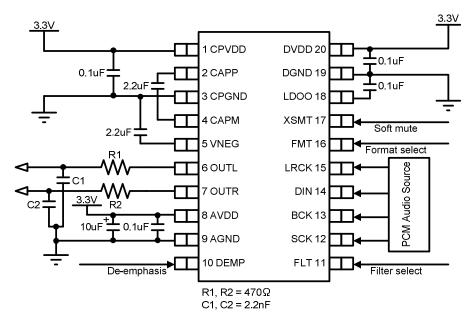


Figure 39. PCM510xA Standard PCM Audio Operation, 3.3V

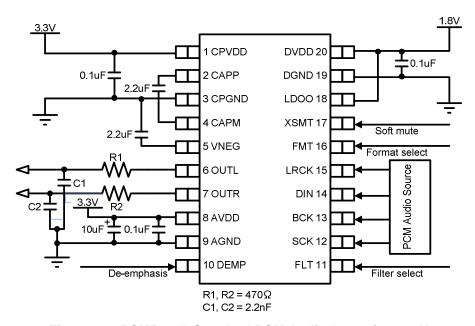


Figure 40. PCM510xA Standard PCM Audio Operation, 1.8V



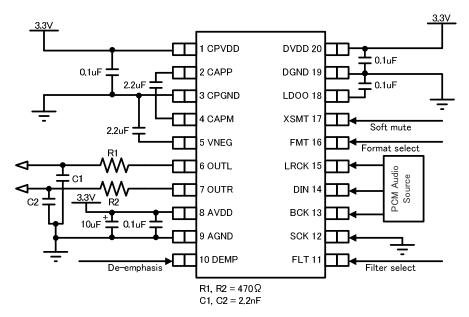


Figure 41. PCM510xA PLL Operation, 3.3V

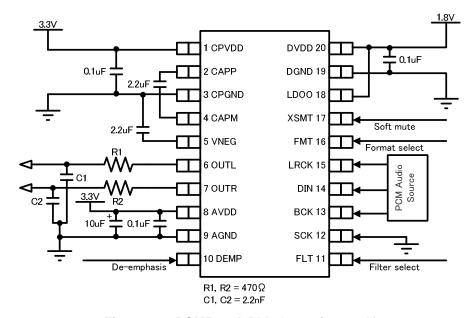


Figure 42. PCM510xA PLL Operation, 1.8V



### Recommended Output Filter for the PCM510xA

The diagram in Figure 43 shows the recommended output filter for the PCM510xA. The new PCM510xA next generation current segment architecture offers excellent out of band noise, making a traditional 20kHz low pass filter a thing of the past.

The RC settings below offer a -3dB filter point at 153kHz (approx), giving the DAC the ability to reproduce virtually all frequencies through to it's maximum sampling rate of 384kHz.

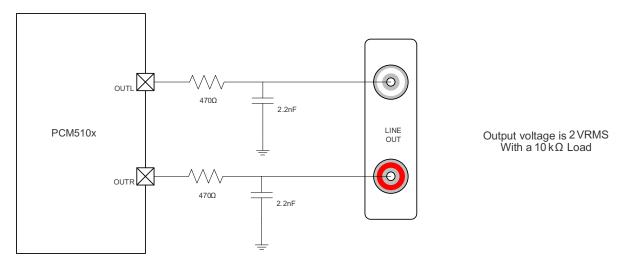


Figure 43. Recommended Output Lowpass Filter for  $10k\Omega$  Operation





11-Apr-2013

#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing		Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
PCM5100APW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	PCM5100A	Samples
PCM5100APWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	PCM5100A	Samples
PCM5101APW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	PCM5101A	Samples
PCM5101APWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	PCM5101A	Samples
PCM5102APW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	PCM5102A	Samples
PCM5102APWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	PCM5102A	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between

the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.



### PACKAGE OPTION ADDENDUM

11-Apr-2013

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# PACKAGE MATERIALS INFORMATION

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### TAPE AND REEL INFORMATION





Α0	
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

All difficultions are florifinal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
PCM5100APWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
PCM5101APWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
PCM5102APWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

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\*All dimensions are nominal

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
PCM5100APWR	TSSOP	PW	20	2000	367.0	367.0	38.0
PCM5101APWR	TSSOP	PW	20	2000	367.0	367.0	38.0
PCM5102APWR	TSSOP	PW	20	2000	367.0	367.0	38.0

PW (R-PDSO-G20)

### PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



# PW (R-PDSO-G20)

# PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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